

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-14 (canceled).

Claim 15 (currently amended): A composite ceramic substrate comprising:  
a ceramic substrate including a surface-mounted component mounted thereon;  
at least one wiring pattern disposed in the ceramic substrate;  
~~at least one a plurality of~~ external terminal electrodes connecting the at least one wiring pattern to a surface electrode of a motherboard;

~~at least one a plurality of~~ convex leg portions made of resin and arranged on the ceramic substrate such that a first end surface of ~~each of the at least one plurality of~~ convex leg portions supports ~~a respective one of the at least one plurality of~~ external terminal electrodes and a second end surface of ~~each of the at least one plurality of~~ convex leg portions opposite to the first end surface is in direct contact with and directly connected to the ceramic substrate; and

a via-hole conductor provided in ~~each of the at least one plurality of~~ convex leg portions and connecting the ~~respective one of the at least one plurality of~~ external terminal electrodes to the at least one wiring pattern; wherein

the plurality of convex leg portions are arranged so as to be spaced apart from one another.

Claim 16 (currently amended): The composite ceramic substrate according to claim 15, wherein the surface-mounted component is mounted on at least one of a first main surface and a second main surface of the ceramic substrate and the plurality of convex leg portions are ~~is~~ disposed on the second main surface of the ceramic substrate.

Claim 17 (currently amended): The composite ceramic substrate according to claim 16, wherein the plurality of convex leg portions ~~are~~ is disposed at a periphery of the second main surface of the ceramic substrate.

Claim 18 (canceled).

Claim 19 (withdrawn-currently amended): The composite ceramic substrate according to claim ~~48~~15, wherein none of the plurality of external terminal electrodes are disposed at corners of the second main surface of the ceramic substrate.

Claim 20 (withdrawn): The composite ceramic substrate according to claim 19, wherein the corners are disposed at a height that is lower than a height at which the external terminal electrodes are disposed.

Claim 21 (withdrawn-currently amended): The composite ceramic substrate according to claim 16, wherein ~~at least one convex leg portions include a plurality of convex leg portions, and~~ the surface-mounted component is mounted between the plurality of convex leg portions on the second main surface.

Claim 22 (withdrawn): The composite ceramic substrate according to claim 21, wherein the surface-mounted component is coated with resin that is the same as the resin from which the plurality of convex leg portions are made.

Claim 23 (withdrawn): The composite ceramic substrate according to claim 22, wherein a round portion is provided between the plurality of convex leg portions and the resin coating the surface-mounted component.

Claim 24 (withdrawn-currently amended): The composite ceramic substrate

according to claim 22, wherein ~~the~~ a surface of the resin coating the surface-mounted component includes a slit.

Claim 25 (withdrawn-currently amended): The composite ceramic substrate according to claim 15, wherein an edge of each of the plurality of convex leg portions has a rounded shape.

Claim 26 (previously presented): The composite ceramic substrate according to claim 15, wherein the via-hole conductor is made of a flexible conductive resin.

Claim 27 (previously presented): The composite ceramic substrate according to claim 15, wherein the ceramic substrate is a multilayer ceramic substrate including a plurality of laminated low temperature co-fired ceramic layers.

Claim 28 (previously presented): The composite ceramic substrate according to claim 15, wherein the surface-mounted component includes an array of external terminal electrodes.